

direction is restrained by preventing the air-cooled heat sink 7 from constraining relative thermal deformation in the horizontal direction of the upper frame 10, frame 5 and wiring board 1.--

IN THE CLAIMS:

Please amend claims 1, 5, 6, and 9, and cancel claims 13 - 15. For convenience all claims are presented.

1. (Amended) A sealing structure for multi-chip modules, comprising:
 - a wiring board having one face mounted with a plurality of semiconductor devices and another face having connecting pins arranged thereover;
 - a frame having a thermal expansion rate compatible with that of the wiring board, provided on the circumference of that face of the wiring board mounted with the semiconductor devices;
 - a cap covering the plurality of semiconductor devices, the cap having a thermal expansion rate different from that of the frame;
 - a heat conducting material provided between the plurality of semiconductor devices and the cap for transmitting heat generated by the plurality of semiconductor devices to the cap;
 - an attachment for fixing the frame and the wiring board to each other; and
 - an intervening member disposed between the frame and the cap such that the frame and the cap are spaced apart, the frame and the cap being joined to each other via the intervening member.
2. A sealing structure for multi-chip modules as in claim 1 wherein the intervening member comprises an elastic substance.
3. A sealing structure for multi-chip modules as in claim 2 wherein the intervening member comprises an O-ring.